ICS 31.180 SLOVENSKÁ TECHNICKÁ NORMA Júl 2022

STN	**Skúšobné metódy na elektrotechnické materiály, dosky s plošnými spojmi a iné spájacie štruktúry a zostavy Časť 2-501: Skúšobné metódy na materiály na spájacie štruktúry Meranie pružnosti a retenčný faktor odolnosti pružných dielektrických materiálov**	**STN EN IEC 61189-2-501** 34 6513

Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 2-501: Test methods for materials for interconnection structures - Measurement of resilience strength and resilience strength retention factor of flexible dielectric materials

Táto norma obsahuje anglickú verziu európskej normy.
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 06/22

Obsahuje: EN IEC 61189-2-501:2022, IEC 61189-2-501:2022

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EUROPEAN STANDARD

NORME EUROPÉENNE

EUROPÄISCHE NORM

EN IEC 61189-2-501

March 2022

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English Version

Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 2-501: Test methods for materials for interconnection structures - Measurement of resilience strength and resilience strength retention factor of flexible dielectric materials (IEC 61189-2-501:2022)

Méthodes d'essai pour les matériaux électriques, les cartes imprimées et autres structures d'interconnexion et ensembles - Partie 2-501: Méthodes d'essai des matériaux pour structures d'interconnexion - Mesure de la puissance élastique et du facteur de rétention de la puissance élastique des matériaux diélectriques flexibles (IEC 61189-2-501:2022)

Prüfverfahren für Elektromaterialien, Leiterplatten und andere Verbindungsstrukturen und Baugruppen - Teil 2-501: Prüfverfahren für Materialien für Verbindungsstrukturen - Messung der Belastbarkeit und Belastbarkeit Rückhaltefaktor flexibler dielektrischer Materialien (IEC 61189-2-501:2022)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

Ref. No. EN IEC 61189-2-501:2022 E

European foreword

The text of document 91/1765/FDIS, future edition 1 of IEC 61189-2-501, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 61189-2-501:2022.

The following dates are fixed:

•	latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement	(dop) 2022-12-10
•	latest date by which the national standards conflicting with the document have to be withdrawn	(dow) 2025-03-10

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The text of the International Standard IEC 61189-2-501:2022 was approved by CENELEC as a European Standard without any modification.

IEC 61189-2-501

Edition 1.0 2022-02

INTERNATIONAL STANDARD

NORME INTERNATIONALE

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

COMMISSION ELECTROTECHNIQUE INTERNATIONALE

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

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IEC 61189-2-501 has been prepared by IEC technical committee TC 91: Electronics assembly technology. It is an International Standard.

The text of this International Standard is based on the following documents:

Draft	Report on voting
91/1765/FDIS	91/1774/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/standardsdev/publications.

A list of all parts in the IEC 61189 series, published under the general title *Test methods for electrical materials, printed boards and other interconnection structures and assemblies*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARDS AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –

Part 2-501: Test methods for materials for interconnection structures – Measurement of resilience strength and resilience strength retention factor of flexible dielectric materials

1 Scope

This part of IEC 61189 establishes a method suitable for testing the softness of FCCL (Flexible Copper Clad Laminate) products and related materials. This method determines the resilience under specified conditions. The test is performed on the sample as manufactured and without conditioning. The test does not apply to the resilience force lower than 10 mN.

2 Normative references

There are no normative references in this document.